# **Octal Bus Transceiver**

# With 5 V-Tolerant Inputs

The MC74LVX245 is an advanced high speed CMOS octal bus transceiver.

It is intended for two-way asynchronous communication between data buses. The direction of data transmission is determined by the level of the  $T/\overline{R}$  input. The output enable pin  $(\overline{OE})$  can be used to disable the device, so that the buses are effectively isolated.

All inputs are equipped with protection circuits against static discharge.

### **Features**

- High Speed:  $t_{PD} = 4.7 \text{ ns (Typ)}$  at  $V_{CC} = 3.3 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 4 \mu A$  (Max) at  $T_A = 25^{\circ}C$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise:  $V_{OLP} = 0.8 \text{ V (Max)}$
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: Human Body Model > 2000 V; Machine Model > 200 V
- These Devices are Pb-Free and are RoHS Compliant

# **Application Notes**

- Do Not Force a Signal on an I/O Pin when it is an Active Output, Damage May Occur
- All Floating (High Impedance) Input or I/O Pins must be Fixed by Means of Pullup or Pulldown Resistors or Bus Terminator ICs
- A Parasitic Diode is Formed between the Bus and V<sub>CC</sub> Terminals Therefore, the LVX245 cannot be Used to Interface 5.0 V to 3.0 V Systems Directly



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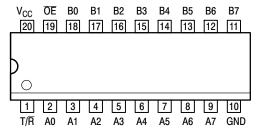






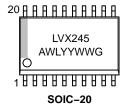
TSSOP-20 DT SUFFIX CASE 948E

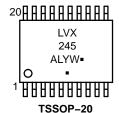
# **PIN ASSIGNMENT**



20-Lead (Top View)

### **MARKING DIAGRAMS**





LVX245 = Specific Device Code A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week G or = Pb-Free Package

(Note: Microdot may be in either location)

# ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

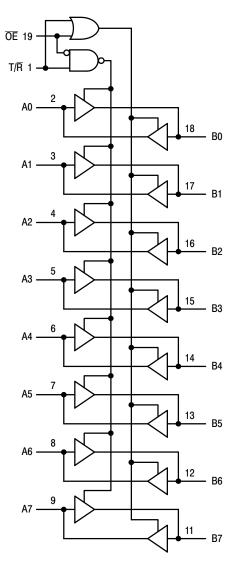


Figure 1. Logic Diagram

**Table 1. PIN NAMES** 

Pins	Function
OE	Output Enable Input
T/R	Transmit/Receive Input
A0–A7	Side A 3-State Inputs or 3-State Outputs
Bo–B7	Side B 3-State Inputs or 3-State Outputs

INP	JTS	OPERATING MODE
OE	T/R	Non-Inverting
L	L	B Data to A Bus
L	Н	A Data to B Bus
Н	Х	Z

 $\label{eq:Hamiltonian} H = \mbox{High Voltage Level; L = Low Voltage Level; Z = \mbox{High Impedance State;}} \\ X = \mbox{High or Low Voltage Level and Transitions are Acceptable; For I_{CC} reasons, Do Not Float Inputs}$ 

### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
V <sub>in</sub>	DC Input Voltage (T/R, OE)	-0.5 to +7.0	V
V <sub>I/O</sub>	DC Output Voltage	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Diode Current	-20	mA
I <sub>OK</sub>	Output Diode Current	±20	mA
l <sub>out</sub>	DC Output Current, per Pin	±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±75	mA
P <sub>D</sub>	Power Dissipation	180	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Max	Unit
V <sub>CC</sub>	DC Supply Voltage		3.6	V
V <sub>in</sub>	DC Input Voltage (T/R, OE)		5.5	V
V <sub>I/O</sub>	DC Output Voltage	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types		+85	°C
Δt/ΔV	Input Rise and Fall Time	0	100	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

# DC ELECTRICAL CHARACTERISTICS

			V <sub>CC</sub>	Т	A = 25°	С	$T_A = -40$	to 85°C	
Symbol	Parameter	Test Conditions	V	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input Voltage		2.0 3.0 3.6	1.5 2.0 2.4			1.5 2.0 2.4		V
V <sub>IL</sub>	Low-Level Input Voltage		2.0 3.0 3.6			0.5 0.8 0.8		0.5 0.8 0.8	V
V <sub>OH</sub>	High-Level Output Voltage (V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub> )	$I_{OH} = -50 \mu A$ $I_{OH} = -50 \mu A$ $I_{OH} = -4 \text{ mA}$	2.0 3.0 3.0	1.9 2.9 2.58	2.0 3.0		1.9 2.9 2.48		V
V <sub>OL</sub>	Low-Level Output Voltage (V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub> )	I <sub>OL</sub> = 50 μA I <sub>OL</sub> = 50 μA I <sub>OL</sub> = 4 mA	2.0 3.0 3.0		0.0 0.0	0.1 0.1 0.36		0.1 0.1 0.44	V
I <sub>in</sub>	Input Leakage Current	$V_{in} = 5.5 \text{ V or GND}$ (T/R, $\overline{\text{OE}}$ )	3.6			±0.1		±1.0	μΑ
l <sub>OZ</sub>	Maximum 3–State Leakage Current	$V_{in} = V_{IL} \text{ or } V_{IH}$ $V_{out} = V_{CC} \text{ or GND}$	3.6			±0.2 5		±2.5	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>in</sub> = V <sub>CC</sub> or GND	3.6			4.0		40.0	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$ )

				Т	A = 25°	С	$T_A = -40$	to 85°C	
Symbol	Parameter	Test Cond	ditions	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay Input to Output	V <sub>CC</sub> = 2.7 V	$C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		6.1 8.6	10.7 14.2	1.0 1.0	13.5 17.0	ns
		$V_{CC} = 3.3 \pm 0.3 \text{ V}$	$C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		4.7 7.2	6.6 10.1	1.0 1.0	8.0 11.5	
t <sub>PZL</sub> , t <sub>PZH</sub>	Output Enable Time to High and Low Level	$V_{CC} = 2.7 \text{ V}$ $R_L = 1 \text{ k}\Omega$	$C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		9.0 11.5	16.9 20.4	1.0 1.0	20.5 24.0	ns
		$V_{CC} = 3.3 \pm 0.3 \text{ V}$ $R_L = 1 \text{ k}\Omega$	$C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		7.1 9.6	11.0 14.5	1.0 1.0	13.0 16.5	
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Output Disable Time From High and Low Level	$V_{CC} = 2.7 \text{ V}$ $R_L = 1 \text{ k}\Omega$	C <sub>L</sub> = 50 pF		11.5	18.0	1.0	21.0	ns
		$V_{CC} = 3.3 \pm 0.3 \text{ V}$ $R_L = 1 \text{ k}\Omega$	C <sub>L</sub> = 50 pF		9.6	12.8	1.0	14.5	
toshl toslh	Output-to-Output Skew (Note 1)	$V_{CC} = 2.7 \text{ V}$ $V_{CC} = 3.3 \pm 0.3 \text{ V}$	$C_L = 50 \text{ pF}$ $C_L = 50 \text{ pF}$			1.5 1.5		1.5 1.5	ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

# **CAPACITIVE CHARACTERISTICS**

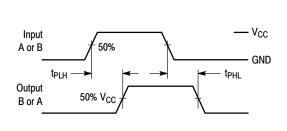
		Т	A = 25°	С	$T_A = -40$	to 85°C	
Symbol	Parameter	Min	Тур	Max	Min	Max	Unit
C <sub>in</sub>	Input Capacitance (T/R, OE)		4	10		10	pF
C <sub>I/O</sub>	Maximum 3-State I/O Capacitance		8				pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 2)		21				pF

<sup>2.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>/8 (per bit). C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

# **NOISE CHARACTERISTICS** (Input $t_r = t_f = 3.0$ ns, $C_L = 50$ pF, $V_{CC} = 3.3$ V, Measured in SOIC Package)

			25°C	
Symbol	Characteristic		Max	Unit
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>		0.8	V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>		-0.8	V
V <sub>IHD</sub>	Minimum High Level Dynamic Input Voltage		2.0	V
V <sub>ILD</sub>	Maximum Low Level Dynamic Input Voltage	0.8		V

# **SWITCHING WAVEFORMS**

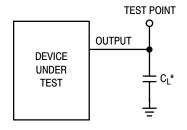


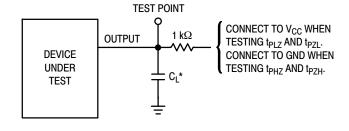
 $V_{CC}$ 50% GND  $\nu_{\text{CC}}$ 50% V<sub>CC</sub> 50% V<sub>CC</sub> ΟE GND -t<sub>PZL</sub> t<sub>PLZ</sub> HIGH **IMPEDANCE** 50% V<sub>CC</sub> A or B V<sub>OL</sub> +0.3V t<sub>PZH</sub> t<sub>PHZ</sub> - $V_{OH}$  -0.3V50% V<sub>CC</sub> A or B HIGH **IMPEDANCE** 

Figure 2.

Figure 3.

# **TEST CIRCUITS**





\*Includes all probe and jig capacitance

**Figure 4. Propagation Delay Test Circuit** 

Figure 5. 3-State Test Circuit

# **ORDERING INFORMATION**

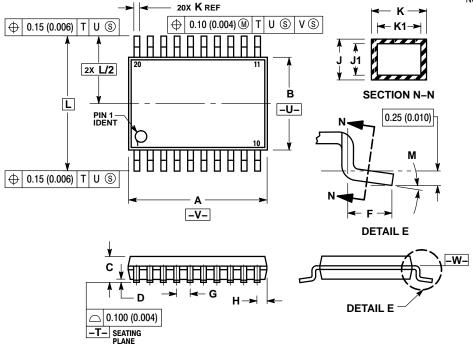
Device	Package	Shipping <sup>†</sup>
MC74LVX245DWR2G	SOIC-20 (Pb-Free)	1000 / Tape & Reel
MC74LVX245DTR2G	TSSOP-20 (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>Includes all probe and jig capacitance

# PACKAGE DIMENSIONS

# TSSOP-20 CASE 948E-02 **ISSUE C**



### NOTES:

- OTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION:
  MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

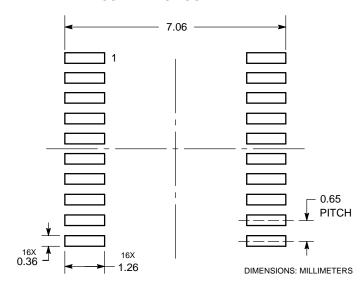
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BC 0.08 (0.003) TOTAL IN EXCESS OF THE K
- (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL
- CONDITION.

  5. TERMINAL NUMBERS ARE SHOWN FOR
- 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	6.40	6.60	0.252	0.260	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.27	0.37	0.011	0.015	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252	BSC	
М	00	00	n٥	ο ο	

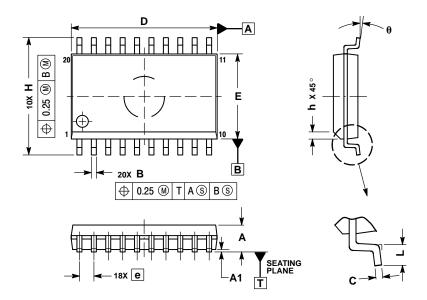
# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### PACKAGE DIMENSIONS

SOIC-20 CASE 751D-05 **ISSUE G** 



### NOTES:

- DIMENSIONS ARE IN MILLIMETERS.
- INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M. 1994.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS				
DIM	MIN MAX				
Α	2.35	2.65			
A1	0.10	0.25			
В	0.35	0.49			
C	0.23	0.32			
D	12.65	12.95			
Е	7.40	7.60			
е	1.27	BSC			
Н	10.05	10.55			
h	0.25	0.75			
L	0.50	0.90			
θ	0 °	7 °			

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